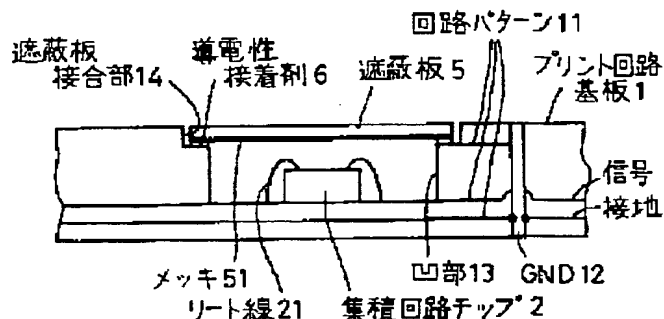


TITLE : PRINTED CIRCUIT DEVICE



**ABSTRACT :** PROBLEM TO BE SOLVED: To improve the space factor of a printed circuit device without protruding an integrated circuit chip from a printed circuit device on which the integrated circuit chip is electrically and mechanically connected to a printed circuit board, to bring the printed circuit device into the state of high density, and to improve the weatherability, the shock-resisting property and other characteristics of the integrated circuit chip.

**SOLUTION:** In a printed circuit device on which an integrated circuit chip 2 is circuit-connected and fixed to a printed circuit board 1, a recessed part 13 is formed on the printed circuit board 1, the integrated circuit chip 2 is housed in the recessed part 13 and it is covered by a shielding plate 5.

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